Integrated Device Technology, Inc. 6024 Silver Creek Valley Road, San Jose, CA - 95138 PRODUCT/PROCESS CHANGE NOTICE (PCN)				
PCN #: A1503-02 (R1) DATE: 2-Oct-2015	MEANS OF DISTINGUISHING CHANGED DEVICES:			
Product Affected: TSSOP-28 Refer to Attachment II for the affected part numbers	<ul> <li>Product Mark</li> <li>Back Mark</li> <li>Date Code</li> <li>Other</li> <li>Lot # will have: "A" prefix for OSET, Taiwan</li> </ul>			
Date Effective:2-Jan-2016				
Contact: IDT PCN DESK	Attachment: Yes No			
E-mail: pcndesk@idt.com	Samples: Please contact your local sales representative for sample request.			
DESCRIPTION AND PURPOSE OF CHANGE:				
<ul> <li>Die Technology</li> <li>Wafer Fabrication Process</li> <li>Assembly Process</li> <li>Revision 1: This notification is results as shown in Attachme</li> </ul>	s a follow-up letter advising the completed qualification nt I.			
<ul> <li>□ Equipment</li> <li>□ Material</li> <li>This notification to advise our assembled at Amkor, Philippin</li> </ul>	This notification to advise our customers that IDT is transferring the affected products assembled at Amkor, Philippines (ATP) to OSET, Taiwan (OSET) as ATP will discontinue their assembly tooling for this product.			
□ Data Sheet There is no change to moisture	sensitive level.			
	Attachment I details the qualification data for this change Attachment II details the affected part number list.			
<b>RELIABILITY/QUALIFICATION SUMMARY:</b> Qualification has been successfully completed. There is no chang	e in MSL rating.			
CUSTOMER ACKNOWLEDGMENT OF RECEIPT:				
IDT records indicate that you require written notification of this cl to grant approval or request additional information. If IDT does no it will be assumed that this change is acceptable. IDT reserves the right to ship either version manufactured after the on the earlier version has been depleted.	ot receive acknowledgement within 30 days of this notice			
Customer:	Approval for shipments prior to effective date.			
Name/Date:	E-Mail Address:			
Title:	Phone# /Fax# :			
CUSTOMER COMMENTS:				
IDT ACKNOWLEDGMENT OF RECEIPT:				
RECD. BY:	DATE:			



Integrated Device Technology, Inc. 6024 Silver Creek Valley Road, San Jose, CA - 95138

# **PRODUCT/PROCESS CHANGE NOTICE (PCN)**

### ATTACHMENT I - PCN # : A1503-02 (R1)

PCN Type:	Manufacturing Site - Transfer Assembly Location
Data Sheet Change:	None
Detail Of Change:	

This notification is to advise our customers that IDT is transferring the affected products assembled at Amkor, Philippines (ATP) to OSET, Taiwan (OSET) as ATP will discontinue their assembly tooling for this product. Presently, OSET is a qualified IDT Subcontractor.

The material set details of the current and new assembly location is as shown in Table 1.

There will be no change in form, fit and function of the products including RoHS compliance and MSL rating.

During the transition period, IDT will continue to support customer shipments with inventory built at ATP facility and does not anticipate any impact on the product availability.

We request you to acknowledge receipt of this notification within 30 days of the date of this PCN notification. If you require samples to conduct an evaluation, please make your sample request within 30 days as samples are not built ahead of the change. Please contact your IDT sales representative to request samples or for additional information.

	Current Assembly: ATP	New Assembly: OSET	
Die Attach	Ablestik 8290	EN4900GC	
Wire	Au or Cu wire	Au or PdCu wire	
Mold Compound	EME G700K	CEL- 9200HF	



Integrated Device Technology, Inc. 6024 Silver Creek Valley Road, San Jose, CA - 95138

# **PRODUCT/PROCESS CHANGE NOTICE (PCN)**

### ATTACHMENT I - PCN # : A1503-02 (R1)

**Qualification Test Plans and Results :** 

Qual Plan & Results:	The qualification was performed in accordance with JEDEC47 recommended
	tests
Qual Vehicle:	TSSOP-28 (3 lots)

		Test Results (SS / Rej)		
Test Description	Test Method	Lot 1	Lot 2	Lot 3
* HAST - Unbiased (130 °C/85% RH, 96 Hrs)	JESD22-A118	25/0	25/0	25/0
* Temperature Cycle / Condition B (-55 °C to +125 °C, 700 Cyc)	JESD22-A104	25/0	25/0	25/0
High Temp. Storage Test (150 °C, 1000 Hrs)	JESD22-A103	25/0	25/0	25/0

Note:

\* Test requires moisture pre-conditioning sequence per JESD22-A113 prior to stress test



Integrated Device Technology, Inc. 6024 Silver Creek Valley Road, San Jose, CA - 95138

# **PRODUCT/PROCESS CHANGE NOTICE (PCN)**

### ATTACHMENT II - PCN # : A1503-02 (R1)

#### **Affected Part Numbers**

Part Number	Part Number	Part Number	Part Number
841602AGILF	841604AGILF	841664AGILF	93716AGLF
841602AGILFT	841604AGILFT	841664AGILFT	93716AGLFT
841604AGI-01LF	841654AGILF	87604AGILF	93716BGLF
841604AGI-01LFT	841654AGILFT	87604AGILFT	93716BGLFT